

ULTEM™ RESIN 4211

REGION ASIA

DESCRIPTION

20% Glass fiber filled and PTFE filled, standard flow Polyetherimide (Tg 217C). ECO Conforming.

TYPICAL PROPERTY VALUES

Revision 20170913

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, yld, Type I, 5 mm/min	129	MPa	ASTM D 638
Tensile Strain, brk, Type I, 5 mm/min	3	%	ASTM D 638
Flexural Stress, brk, 2.6 mm/min, 100 mm span	193	MPa	ASTM D 790
Flexural Modulus, 2.6 mm/min, 100 mm span	7100	MPa	ASTM D 790
IMPACT			
Izod Impact, Reverse Notched, 3.2 mm	437	J/m	ASTM D 256
THERMAL			
HDT, 1.82 MPa, 6.4 mm, unannealed	212	°C	ASTM D 648
PHYSICAL			
Specific Gravity	1.48	-	ASTM D 792
Melt Flow Rate, 337°C/6.6 kgf	10.3	g/10 min	ASTM D 1238
INJECTION MOLDING			
Drying Temperature	135	°C	
Drying Time	4 – 6	hrs	
Drying Time (Cumulative)	10	hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	350 – 370	°C	
Nozzle Temperature	350 – 370	°C	
Front - Zone 3 Temperature	350 – 370	°C	
Middle - Zone 2 Temperature	345 – 365	°C	
Rear - Zone 1 Temperature	340 – 360	°C	
Mold Temperature	135 – 165	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	40 – 70	rpm	
Shot to Cylinder Size	40 – 60	%	
Vent Depth	0.025 – 0.076	mm	



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